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Understanding <u>Embedded - FPGAs (Field Programmable Gate Array)</u>

Embedded - FPGAs, or Field Programmable Gate Arrays, are advanced integrated circuits that offer unparalleled flexibility and performance for digital systems. Unlike traditional fixed-function logic devices, FPGAs can be programmed and reprogrammed to execute a wide array of logical operations, enabling customized functionality tailored to specific applications. This reprogrammability allows developers to iterate designs quickly and implement complex functions without the need for custom hardware.

Applications of Embedded - FPGAs

The versatility of Embedded - FPGAs makes them indispensable in numerous fields. In telecommunications.

Details	
Product Status	Obsolete
Number of LABs/CLBs	7362
Number of Logic Elements/Cells	156000
Total RAM Bits	11746304
Number of I/O	336
Number of Gates	-
Voltage - Supply	1.07V ~ 1.13V
Mounting Type	Surface Mount
Operating Temperature	0°C ~ 85°C (TJ)
Package / Case	672-BBGA, FCBGA
Supplier Device Package	672-FBGA (27x27)
Purchase URL	https://www.e-xfl.com/product-detail/intel/5agxba3d6f27c6n

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Address: Room A, 16/F, Full Win Commercial Centre, 573 Nathan Road, Mongkok, Hong Kong

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Symbol	Description	V _{CCIO} (V)	Value	Unit
		3.0	0.189	
		2.5	0.208	
	OCT variation with temperature without recalibration	1.8	0.266	
dR/dT		1.5	0.273	%/°C
		1.35	0.200	
		1.25	0.200	
		1.2	0.317	

Pin Capacitance

Table 1-11: Pin Capacitance for Arria V Devices

Symbol	Description	Maximum	Unit
C_{IOTB}	Input capacitance on top/bottom I/O pins	6	pF
C_{IOLR}	Input capacitance on left/right I/O pins	6	pF
C_{OUTFB}	Input capacitance on dual-purpose clock output/feedback pins	6	pF
C _{IOVREF}	Input capacitance on V _{REF} pins	48	pF

Hot Socketing

Table 1-12: Hot Socketing Specifications for Arria V Devices

Symbol	Description	Maximum	Unit
I _{IOPIN (DC)}	DC current per I/O pin	300	μΑ
I _{IOPIN (AC)}	AC current per I/O pin	8 ⁽¹⁰⁾	mA
I _{XCVR-TX (DC)}	DC current per transceiver transmitter (TX) pin	100	mA

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I/O Standard	V _{CCIO} (V)		V _{ID} (mV) ⁽¹⁶⁾			V _{ICM(DC)} (V)		V _{OD} (V) ⁽¹⁷⁾		V _{OCM} (V) ⁽¹⁷⁾⁽¹⁸⁾						
I/O Standard	Min	Тур	Max	Min	Condition	Max	Min	Condition	Max	Min	Тур	Max	Min	Тур	Max	
PCML	PCML Transmitter, receiver, and input reference clock pins of high-speed transceivers use the PCML I/O standard. For transmitter, receiver, and reference clock I/O pin specifications, refer to Transceiver Specifications for Arria V GX and SX Devices and Transceiver Specifications for Arria V GT and ST Devices tables.															
2.5 V	2.5 V 1 DC(19) 2.375 2.5 2.625 100	V _{CM} =	$V_{CM} = $	0.247	0.245	0.6	0.6 1.125	1.25	1.375							
LVDS ⁽¹⁹⁾	2.373	2.3	2.023	525 100	1.25 V	1.25 V	_	1.05	$D_{MAX} >$ 1.25 Gbps	1.55	0.247	_	0.0	1.123	1.23	1.373
RSDS (HIO) ⁽²⁰⁾	2.375	2.5	2.625	100	V _{CM} = 1.25 V	_	0.25	_	1.45	0.1	0.2	0.6	0.5	1.2	1.4	
Mini-LVDS (HIO) ⁽²¹⁾	2.375	2.5	2.625	200	_	600	0.300	_	1.425	0.25	_	0.6	1	1.2	1.4	
LVPECL ⁽²²⁾			200	300	200		0.60	D _{MAX} ≤ 700 Mbps	1.80							
LVFECL				300			1.00	D _{MAX} > 700 Mbps	1.60							

• Transceiver Specifications for Arria V GX and SX Devices on page 1-23 Provides the specifications for transmitter, receiver, and reference clock I/O pin.

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 $^{^{(16)}}$ The minimum V_{ID} value is applicable over the entire common mode range, V_{CM} .

 $^{^{(17)}~}R_L$ range: $90 \le R_L \le 110~\Omega.$

⁽¹⁸⁾ This applies to default pre-emphasis setting only.

⁽¹⁹⁾ For optimized LVDS receiver performance, the receiver voltage input range must be within 1.0 V to 1.6 V for data rates above 1.25 Gbps and 0 V to 1.85 V for data rates below 1.25 Gbps.

 $^{^{\}left(20\right)}$ For optimized RSDS receiver performance, the receiver voltage input range must be within 0.25 V to 1.45 V.

 $^{^{\}left(21\right)}$ For optimized Mini-LVDS receiver performance, the receiver voltage input range must be within 0.3 V to 1.425 V.

For optimized LVPECL receiver performance, the receiver voltage input range must be within 0.85 V to 1.75 V for data rates above 700 Mbps and 0.45 V to 1.95 V for data rates below 700 Mbps.

Transceiver Specifications for Arria V GT and ST Devices on page 1-29
 Provides the specifications for transmitter, receiver, and reference clock I/O pin.

Switching Characteristics

This section provides performance characteristics of Arria V core and periphery blocks.

Transceiver Performance Specifications

Transceiver Specifications for Arria V GX and SX Devices

Table 1-20: Reference Clock Specifications for Arria V GX and SX Devices

Symbol/Description	Condition	Trans	Transceiver Speed Grade 4			Transceiver Speed Grade 6			
Symbol/Description	Condition	Min	Тур	Max	Min	Тур	Max	Unit	
Supported I/O standards	1.2 V PCM	L, 1.4 V PCN	L,1.5 V PCML	, 2.5 V PCMI	L, Differentia	LVPECL ⁽²³⁾ ,	HCSL, and	LVDS	
Input frequency from REFCLK input pins	_	27	_	710	27	_	710	MHz	
Rise time	Measure at ±60 mV of differential signal ⁽²⁴⁾	_	_	400	_	_	400	ps	
Fall time	Measure at ±60 mV of differential signal ⁽²⁴⁾	_	_	400	_	_	400	ps	
Duty cycle	_	45	_	55	45	_	55	%	
Peak-to-peak differential input voltage	_	200	_	300 ⁽²⁵⁾ / 2000	200	_	300 ⁽²⁵⁾ / 2000	mV	

Send Feedback

⁽²³⁾ Differential LVPECL signal levels must comply to the minimum and maximum peak-to-peak differential input voltage specified in this table.

⁽²⁴⁾ REFCLK performance requires to meet transmitter REFCLK phase noise specification.

⁽²⁵⁾ The maximum peak-to peak differential input voltage of 300 mV is allowed for DC coupled link.

Symbol/Description	Condition	Т	Unit			
3ymbol/Description	Condition	Min	Тур	Max	Offic	
$t_{\mathrm{LTD_manual}}^{(51)}$	_	4	_	_	μs	
t _{LTR_LTD_manual} ⁽⁵²⁾	_	15	_	_	μs	
Programmable ppm detector ⁽⁵³⁾	_	±62.5, 100, 125, 200, 250, 300, 500, and 1000			ppm	
Run length	_	_	_	200	UI	
Programmable equalization AC and DC gain	AC gain setting = 0 to $3^{(54)}$ DC gain setting = 0 to 1	Refer to CTLE Response at Data Rates > 3.25 Gbps across Supported AC Gain and DC Gain for Arria V GX, GT, SX, and ST Devices and CTLE Response at Data Rates ≤ 3.25 Gbps across Supported AC Gain and DC Gain for Arria V GX, GT, SX, and ST Devices diagrams.				

Table 1-29: Transmitter Specifications for Arria V GT and ST Devices

Symbol/Description	Condition	Tran	sceiver Speed Gra	Unit		
	Condition	Min	Тур	Max	Offic	
Supported I/O standards	1.5 V PCML					
Data rate (6-Gbps transceiver)	_	611	_	6553.6	Mbps	
Data rate (10-Gbps transceiver)	_	0.611	_	10.3125	Gbps	
V _{OCM} (AC coupled)	_	_	650	_	mV	
V _{OCM} (DC coupled)	≤ 3.2 Gbps ⁽⁴⁸⁾	670	700	730	mV	

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 t_{LTD_manual} is the time required for the receiver CDR to start recovering valid data after the rx_is_lockedtodata signal goes high when the CDR is functioning in the manual mode.

 $t_{LTR_LTD_manual}$ is the time the receiver CDR must be kept in lock to reference (LTR) mode after the rx_is_lockedtoref signal goes high when the CDR is functioning in the manual mode.

⁽⁵³⁾ The rate match FIFO supports only up to ± 300 ppm.

⁽⁵⁴⁾ The Quartus Prime software allows AC gain setting = 3 for design with data rate between 611 Mbps and 1.25 Gbps only.

Symbol	V _{OD} Setting ⁽⁵⁸⁾	V _{OD} Value (mV)	V _{OD} Setting ⁽⁵⁸⁾	V _{OD} Value (mV)
	25	500	53	1060
	26	520	54	1080
	27	540	55	1100
	28	560	56	1120
	29	580	57	1140
	30	600	58	1160
	31	620	59	1180
	32	640	60	1200
	33	660		

Transmitter Pre-Emphasis Levels

The following table lists the simulation data on the transmitter pre-emphasis levels in dB for the first post tap under the following conditions:

- Low-frequency data pattern—five 1s and five 0s
- Data rate—2.5 Gbps

The levels listed are a representation of possible pre-emphasis levels under the specified conditions only and the pre-emphasis levels may change with data pattern and data rate.

Arria V devices only support 1st post tap pre-emphasis with the following conditions:

- The 1st post tap pre-emphasis settings must satisfy $|B| + |C| \le 60$ where $|B| = V_{OD}$ setting with termination value, $R_{TERM} = 100 \Omega$ and |C| = 1st post tap pre-emphasis setting.
- |B| |C| > 5 for data rates < 5 Gbps and |B| |C| > 8.25 for data rates > 5 Gbps.
- $(V_{MAX}/V_{MIN} 1)\% < 600\%$, where $V_{MAX} = |B| + |C|$ and $V_{MIN} = |B| |C|$.

Exception for PCIe Gen2 design: V_{OD} setting = 43 and pre-emphasis setting = 19 are allowed for PCIe Gen2 design with transmit de-emphasis – 6dB setting (pipe_txdeemp = 1'b0) using Altera PCIe Hard IP and PIPE IP cores.

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⁽⁵⁸⁾ Convert these values to their binary equivalent form if you are using the dynamic reconfiguration mode for PMA analog controls.

Table 1-34: Transceiver Compliance Specification for All Supported Protocol for Arria V GX, GT, SX, and ST Devices

Protocol	Sub-protocol	Data Rate (Mbps)
	PCIe Gen1	2,500
PCIe	PCIe Gen2	5,000
	PCIe Cable	2,500
XAUI	XAUI 2135	3,125
	SRIO 1250 SR	1,250
	SRIO 1250 LR	1,250
	SRIO 2500 SR	2,500
	SRIO 2500 LR	2,500
	SRIO 3125 SR	3,125
Serial RapidIO® (SRIO)	SRIO 3125 LR	3,125
Serial Rapidio (SRIO)	SRIO 5000 SR	5,000
	SRIO 5000 MR	5,000
	SRIO 5000 LR	5,000
	SRIO_6250_SR	6,250
	SRIO_6250_MR	6,250
	SRIO_6250_LR	6,250

Figure 1-9: SPI Master Timing Diagram

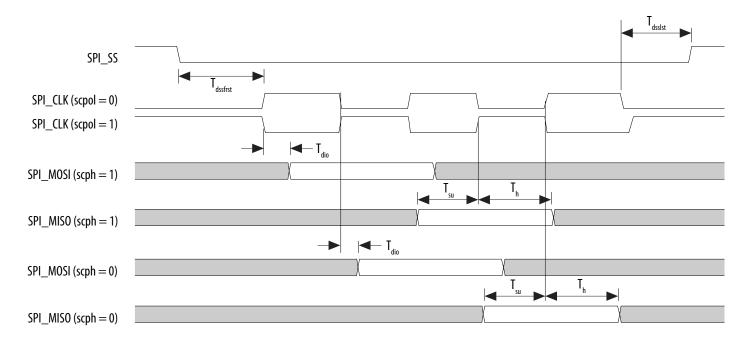


Table 1-53: SPI Slave Timing Requirements for Arria V Devices

The setup and hold times can be used for Texas Instruments SSP mode and National Semiconductor Microwire mode.

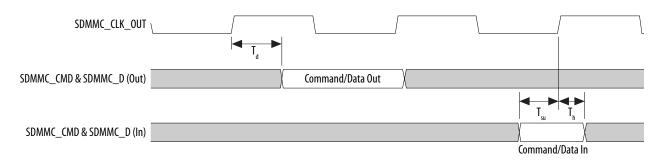
Symbol	Description	Min	Max	Unit
T_{clk}	CLK clock period	20	_	ns
T_s	MOSI Setup time	5	_	ns
T_h	MOSI Hold time		_	ns
T_{suss}	Setup time SPI_SS valid before first clock edge	8	_	ns
$T_{ m hss}$	T _{hss} Hold time SPI_SS valid after last clock edge		_	ns
T_d	MISO output delay	_	6	ns

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Figure 1-11: SD/MMC Timing Diagram



Booting and Configuration Chapter, Arria V Hard Processor System Technical Reference Manual

Provides more information about CSEL pin settings in the SD/MMC Controller CSEL Pin Settings table.

USB Timing Characteristics

PHYs that support LPM mode may not function properly with the USB controller due to a timing issue. It is recommended that designers use the MicroChip USB3300 PHY device that has been proven to be successful on the development board.

Table 1-55: USB Timing Requirements for Arria V Devices

Symbol	Description	Min	Тур	Max	Unit
T_{clk}	USB CLK clock period	_	16.67	_	ns
T_d	CLK to USB_STP/USB_DATA[7:0] output delay	4.4	_	11	ns
T_{su}	Setup time for USB_DIR/USB_NXT/USB_DATA[7:0]	2	_	_	ns
T_h	Hold time for USB_DIR/USB_NXT/USB_DATA[7:0]	1	_	_	ns

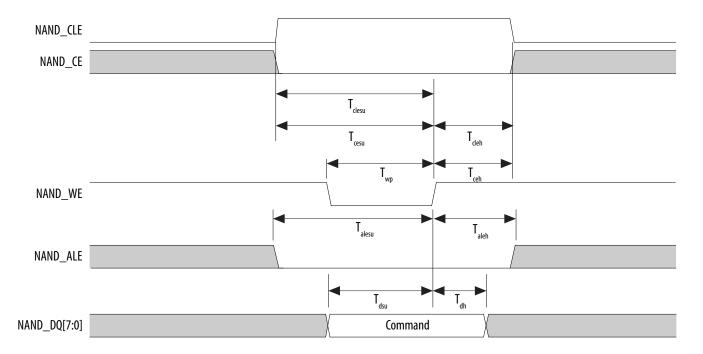
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Symbol	Description	Min	Max	Unit
$T_{dh}^{(89)}$	Data to write enable hold time	5	_	ns
T_{cea}	Chip enable to data access time	_	25	ns
T _{rea}	Read enable to data access time	_	16	ns
$T_{\rm rhz}$	Read enable to data high impedance	_	100	ns
T_{rr}	Ready to read enable low	20	_	ns

Figure 1-17: NAND Command Latch Timing Diagram



Symbol	Parameter	Minimum	Maximum	Unit
t_{CD2CU}	CONF_DONE high to CLKUSR enabled	4 × maximum DCLK period	_	_
t _{CD2UMC}	CONF_DONE high to user mode with CLKUSR option on	t_{CD2CU} + (T_{init} × CLKUSR period)	_	_
T _{init}	Number of clock cycles required for device initialization	8,576	_	Cycles

FPP Configuration Timing

Provides the FPP configuration timing waveforms.

AS Configuration Timing

Table 1-68: AS Timing Parameters for AS ×1 and ×4 Configurations in Arria V Devices

The minimum and maximum numbers apply to both the internal oscillator and CLKUSR when either one is used as the clock source for device configuration.

The t_{CF2CD} , t_{CF2ST0} , t_{CFG} , t_{STATUS} , and t_{CF2ST1} timing parameters are identical to the timing parameters for passive serial (PS) mode listed in PS Timing Parameters for Arria V Devices table. You can obtain the t_{CF2ST1} value if you do not delay configuration by externally holding <code>nstatus</code> low.

Symbol	Parameter	Minimum	Maximum	Unit
t_{CO}	DCLK falling edge to the AS_DATAO/ASDO output	_	2	ns
t _{SU}	Data setup time before the falling edge on DCLK	1.5	_	ns
t _{DH}	Data hold time after the falling edge on DCLK	0		ns
t _{CD2UM}	CONF_DONE high to user mode	175	437	μs
t_{CD2CU}	CONF_DONE high to CLKUSR enabled	4 × maximum DCLK period	_	_
t _{CD2UMC}	CONF_DONE high to user mode with CLKUSR option on	t_{CD2CU} + (T_{init} × CLKUSR period)	_	_
$T_{\rm init}$	Number of clock cycles required for device initialization	8,576	_	Cycles

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Variant	Member Code	Configuration .rbf Size (bits)	IOCSR .rbf Size (bits)
	A1	71,015,712	439,960
	A3	71,015,712	439,960
	A5	101,740,800	446,360
Arria V GX	A7	101,740,800	446,360
Allia V GA	B1	137,785,088	457,368
	В3	137,785,088	457,368
	B5	185,915,808	463,128
	B7	185,915,808	463,128
	C3	71,015,712	439,960
Arria V GT	C7	101,740,800	446,360
Ailia V G1	D3	137,785,088	457,368
	D7	185,915,808	463,128
Arria V SX	В3	185,903,680	450,968
Airia V SA	B5	185,903,680	450,968
Arria V ST	D3	185,903,680	450,968
7111a V 31	D5	185,903,680	450,968

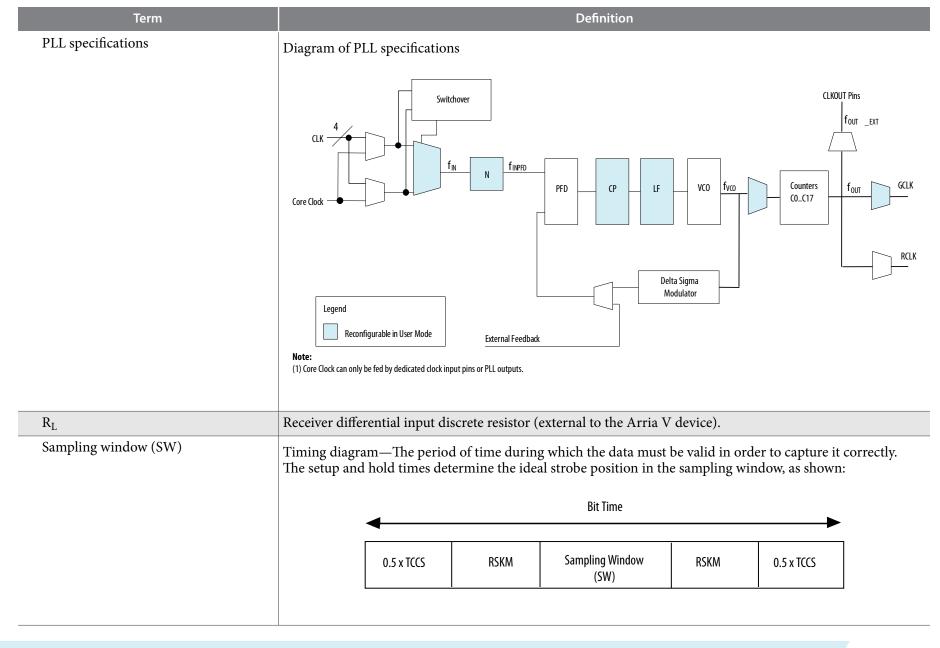
Minimum Configuration Time Estimation

Table 1-73: Minimum Configuration Time Estimation for Arria V Devices

The estimated values are based on the configuration .rbf sizes in Uncompressed .rbf Sizes for Arria V Devices table.

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Date	Version	Changes
January 2015	2015.01.30	$ullet$ Updated the description for $V_{CC_AUX_SHARED}$ to "HPS auxiliary power supply" in the following tables:
		Absolute Maximum Ratings for Arria V Devices
		HPS Power Supply Operating Conditions for Arria V SX and ST Devices
		• Added statement in I/O Standard Specifications: You must perform timing closure analysis to determine the maximum achievable frequency for general purpose I/O standards.
		• Updated the conditions for transceiver reference clock rise time and fall time: Measure at ±60 mV of differential signal. Added a note to the conditions: REFCLK performance requires to meet transmitter REFCLK phase noise specification.
		Updated the description in Periphery Performance Specifications to mention that proper timing closure is required in design.
		• Updated HPS Clock Performance main_base_clk specifications from 525 MHz (for -I3 speed grade) and 462 MHz (for -C4 speed grade) to 400 MHz.
		• Updated HPS PLL VCO maximum frequency to 1,600 MHz (for -C5, -I5, and -C6 speed grades), 1,850 MHz (for -C4 speed grade), and 2,100 MHz (for -I3 speed grade).
		Changed the symbol for HPS PLL input jitter divide value from NR to N.
		• Removed "Slave select pulse width (Texas Instruments SSP mode)" parameter from the following tables:
		SPI Master Timing Requirements for Arria V Devices
		SPI Slave Timing Requirements for Arria V Devices
		 Added descriptions to USB Timing Characteristics section in HPS Specifications: PHYs that support LPM mode may not function properly with the USB controller due to a timing issue. It is recommended that designers use the MicroChip USB3300 PHY device that has been proven to be successful on the development board.
		Added HPS JTAG timing specifications.
		• Updated FPGA JTAG timing specifications note as follows: A 1-ns adder is required for each $V_{\rm CCIO}$ voltage step down from 3.0 V. For example, $t_{\rm JPCO}$ = 13 ns if $V_{\rm CCIO}$ of the TDO I/O bank = 2.5 V, or 14 ns if it equals 1.8 V.
		$ \hbox{ - Updated the value in the V_{ICM} (AC Coupled) row and in note 6 from 650 mV to 750 mV in the Transceiver Specifications for Arria V GT and ST Devices table. } \\$

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I/O Standard Specifications

The V_{OL} and V_{OH} values are valid at the corresponding I_{OH} and I_{OL} , respectively.

Table 2-16: Single-Ended I/O Standards for Arria V GZ Devices

I/O Standard		V _{CCIO} (V)		V _{II}	_(V)	V _{IH}	(V)	V _{OL} (V)	V _{OH} (V)	I _{OL} (mA)	I _{OH} (mA)
i/O Staildaid	Min	Тур	Max	Min	Max	Min	Max	Max	Min	IOL (IIIA)	IOH (IIIA)
LVTTL	2.85	3	3.15	-0.3	0.8	1.7	3.6	0.4	2.4	2	-2
LVCMOS	2.85	3	3.15	-0.3	0.8	1.7	3.6	0.2	V _{CCIO} - 0.2	0.1	-0.1
2.5 V	2.375	2.5	2.625	-0.3	0.7	1.7	3.6	0.4	2	1	-1
1.8 V	1.71	1.8	1.89	-0.3	$0.35 \times V_{\rm CCIO}$	$0.65 \times V_{\rm CCIO}$	V _{CCIO} + 0.3	0.45	V _{CCIO} - 0.45	2	-2
1.5 V	1.425	1.5	1.575	-0.3	$0.35 \times V_{\rm CCIO}$	$0.65 \times V_{\rm CCIO}$	V _{CCIO} + 0.3	$\begin{array}{c} 0.25 \times \\ V_{\rm CCIO} \end{array}$	$0.75 \times V_{\text{CCIO}}$	2	-2
1.2 V	1.14	1.2	1.26	-0.3	$\begin{array}{c} 0.35 \times \\ V_{\rm CCIO} \end{array}$	$0.65 \times V_{\rm CCIO}$	V _{CCIO} + 0.3	$\begin{array}{c} 0.25 \times \\ V_{\rm CCIO} \end{array}$	$0.75 \times V_{\text{CCIO}}$	2	-2

Table 2-17: Single-Ended SSTL, HSTL, and HSUL I/O Reference Voltage Specifications for Arria V GZ Devices

I/O Standard		V _{CCIO} (V)			V _{REF} (V)			V	V _{TT} (V)		
i/O Standard	Min	Тур	Max	Min	Тур	Max	Min	Тур	Max		
SSTL-2 Class I, II	2.375	2.5	2.625	$0.49 \times V_{CCIO}$	$\begin{array}{c} 0.5 \times \\ V_{\rm CCIO} \end{array}$	$0.51 \times V_{\rm CCIO}$	V _{REF} - 0.04	V_{REF}	V _{REF} + 0.04		
SSTL-18 Class I, II	1.71	1.8	1.89	0.833	0.9	0.969	V _{REF} - 0.04	V_{REF}	V _{REF} + 0.04		
SSTL-15 Class I, II	1.425	1.5	1.575	$0.49 \times V_{CCIO}$	$0.5 \times V_{\rm CCIO}$	$0.51 \times V_{\rm CCIO}$	$\begin{array}{c} 0.49 \times \\ V_{CCIO} \end{array}$	0.5 × VCCIO	$0.51 \times V_{CCIO}$		



Symbol/Description	Conditions	Trans	ceiver Spee	d Grade 2	Transc	eiver Spee	ed Grade 3	Unit
Symbol/Description	Conditions	Min	Тур	Max	Min	Тур	Max	Offic
$\label{eq:maximum peak-to-peak differential} \\ input voltage \ V_{ID} \ (diff \ p-p) \ before \\ device \ configuration$	_	_	_	1.6	_	_	1.6	V
Maximum peak-to-peak differential input voltage V _{ID} (diff p-p) after	$V_{\text{CCR_GXB}} = 1.0 \text{ V}$ $(V_{\text{ICM}} = 0.75 \text{ V})$	_	_	1.8	_	_	1.8	V
device configuration (146)	$V_{\text{CCR_GXB}} = 0.85 \text{ V}$ $(V_{\text{ICM}} = 0.6 \text{ V})$	_	_	2.4	_	_	2.4	V
Minimum differential eye opening at receiver serial input pins (147)(148)	_	85	_	_	85	_	_	mV
	85– Ω setting	_	85 ± 30%	_	_	85 ± 30%	_	Ω
Differential on-chip termination	100–Ω setting	_	100 ± 30%	_	_	100 ± 30%	_	Ω
resistors	120–Ω setting	_	120 ± 30%	_	_	120 ± 30%	_	Ω
	150–Ω setting	_	150 ± 30%	_	_	150 ± 30%	_	Ω



The maximum peak to peak differential input voltage V_{ID} after device configuration is equal to $4 \times$ (absolute V_{MAX} for receiver pin - V_{ICM}).

The differential eye opening specification at the receiver input pins assumes that **Receiver Equalization** is disabled. If you enable **Receiver Equalization**, the receiver circuitry can tolerate a lower minimum eye opening, depending on the equalization level.

⁽¹⁴⁸⁾ Minimum eye opening of 85 mV is only for the unstressed input eye condition.

Momory	Mode	Resour	rces Used		Unit			
Memory	Mode	ALUTs	Memory	C 3	C4	I3L	14	Offic
	Single-port, all supported widths	0	1	650	550	500	450	MHz
	Simple dual-port, all supported widths	0	1	650	550	500	450	MHz
	Simple dual-port with the read-during-write option set to Old Data , all supported widths	0	1	455	400	455	400	MHz
M20K Block	Simple dual-port with ECC enabled, 512×32	0	1	400	350	400	350	MHz
	Simple dual-port with ECC and optional pipeline registers enabled, 512×32	0	1	500	450	500	450	MHz
	True dual port, all supported widths	0	1	650	550	500	450	MHz
	ROM, all supported widths	0	1	650	550	500	450	MHz

Temperature Sensing Diode Specifications

Table 2-37: Internal Temperature Sensing Diode Specification

Temperature Range	Accuracy	Offset Calibrated Option	Sampling Rate	Conversion Time	Resolution	Minimum Resolution with no Missing Codes
−40°C to 100°C	±8°C	No	1 MHz, 500 kHz	< 100 ms	8 bits	8 bits

Table 2-38: External Temperature Sensing Diode Specifications for Arria V GZ Devices

Description	Min	Тур	Max	Unit
I _{bias} , diode source current	8	_	200	μΑ
V _{bias,} voltage across diode	0.3	_	0.9	V
Series resistance	_	_	< 1	Ω



Symbol	Parameter	Minimum	Maximum	Unit
$t_{\rm CD2CU}$	CONF_DONE high to CLKUSR enabled	4 × maximum	_	_
		DCLK period		
t _{CD2UM}	CONF_DONE high to user mode with CLKUSR option on	$t_{\text{CD2CU}} + (8576 \times \text{CLKUSR period})$	_	_

- DCLK-to-DATA[] Ratio (r) for FPP Configuration on page 2-57
- Configuration, Design Security, and Remote System Upgrades in Arria V Devices



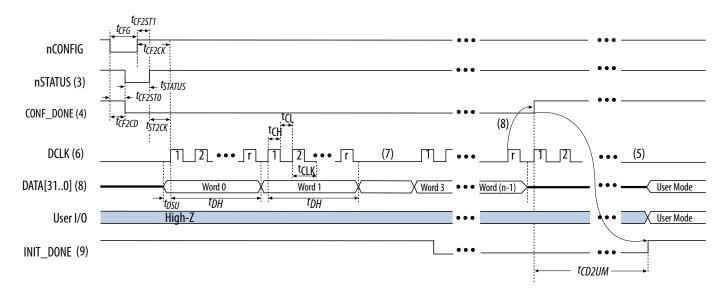
⁽²⁰⁸⁾ The minimum and maximum numbers apply only if you chose the internal oscillator as the clock source for initializing the device.

To enable the CLKUSR pin as the initialization clock source and to obtain the maximum frequency specification on these pins, refer to the "Initialization" section of the *Configuration*, *Design Security, and Remote System Upgrades in Arria V Devices* chapter.

FPP Configuration Timing when DCLK to DATA[] > 1

Figure 2-8: FPP Configuration Timing Waveform When the DCLK-to-DATA[] Ratio is >1,

Timing when using a MAX II device, MAX V device, or microprocessor as an external host.



Notes:

- 1. To find out the DCLK-to-DATA[] ratio for your system, refer to the "DCLK-to-DATA[] Ratio for Arria V GZ Devices" table.
- 2. The beginning of this waveform shows the device in user mode. In user mode, nCONFIG, nSTATUS, and CONF_DONE are at logic high levels. When nCONFIG is pulled low, a reconfiguration cycle begins.
- 3. After power-up, the Arria V GZ device holds nSTATUS low for the time as specified by the POR delay.
- 4. After power-up, before and during configuration, CONF_DONE is low.
- 5. Do not leave DCLK floating after configuration. DCLK is ignored after configuration is complete. It can toggle high or low if required.
- 6. "r" denotes the DCLK-to-DATA[] ratio. For the DCLK-to-DATA[] ratio based on the decompression and the design security feature enable settings, refer to the "DCLK-to-DATA[] Ratio for Arria V GZ Devices" table.
- 7. If needed, pause DCLK by holding it low. When DCLK restarts, the external host must provide data on the DATA[31..0] pins prior to sending the first DCLK rising edge.
- 8. To ensure a successful configuration, send the entire configuration data to the Arria V GZ device. CONF_DONE is released high after the Arria V GZ device receives all the configuration data successfully. After CONF_DONE goes high, send two additional falling edges on DCLK to begin initialization and enter user mode.
- 9. After the option bit to enable the INIT_DONE pin is configured into the device, the INIT_DONE goes low.

Altera Corporation Arria V GZ Device Datasheet



Glossary

Table 2-68: Glossary

